



MONDAY MARCH 24, 2025 - WORKSHOP

08:30-09:00	Registration	
09:00-09:15	Opening - Christopher J. Wilson	
09:15-09:55	Anand Murthy (Lam, USA) The Metallization Routing to Two Trillion Dollars	
09:55-10:35	Henrik H. Sønsteby (University of Oslo, Norway) From stamp to wafer - How complex ALD processes become exponentially harder to control on fab-friendly scale	
10:35-11:05		Coffee Break
11:05-11:45	Robert Clark (TEL, USA) Selective and Self-Limited Process Technologies to Enable Ångstrom Scale Integrated Circuits	
11:45-12:25	Mikko Ritala (University of Helsinki, Finland) ALD and AS-ALD of Metallic Films with New Precursors and Approaches	
12:25-13:25		Lunch
13:25-14:05	Chiyu Zhu (ASM, Finland) Time for ALD Metals: Enabling the next generation of leading-edge devices	
14:05-14:45	Hubert Renevier (LMGP, Univ. Grenoble Alpes, CNRS, Grenoble-INP, France) In situ study of the synthesis of lamellar metal chalcogenides by alternating deposition of organic & inorganic molecules	
14:45-15:15		Coffee Break
15:15-15:55	Cara-Lena Nies (Tyndall National Institute, Ireland) Understanding and predicting interconnect metal deposition and morphology from atomic scale simulations	
15:55-16:35	Mark Saly (Applied Materials, USA) Next Generation Microelectronics Devices Enabled by Atomic Layer Deposition	
16:35-17:35	Panel discussion	